

## Features

- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- Positive Temperature Coefficient on VF
- Temperature-independent Switching
- 175°C Operating Junction Temperature

## Benefits

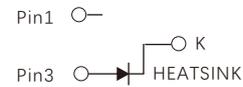
- Replace Bipolar with Unipolar Device
- Reduction of Heat Sink Size
- Parallel Devices Without Thermal Runaway
- Essentially No Switching Losses

## Applications

- Switch Mode Power Supplies
- Power Factor Correction
- Motor drive, PV Inverter, Wind Power Station

## TO-252

SC0865M2



$V_{RRM}$	=	650	V
$I_F (T_C \leq 135^\circ\text{C})$	=	11	A
$Q_C$	=	22	nC

## Maximum Ratings

Symbol	Parameter	Value	Unit	Test Conditions	Note
$V_{RRM}$	Repetitive Peak Reverse Voltage	650	V	$T_J = 25^\circ\text{C}$	
$V_{RSM}$	Surge Peak Reverse Voltage	650	V	$T_J = 25^\circ\text{C}$	
$V_R$	DC Blocking Voltage	650	V	$T_J = 25^\circ\text{C}$	
$I_F$	Forward Current	24 11 8	A	$T_C \leq 25^\circ\text{C}$ $T_C \leq 135^\circ\text{C}$ $T_C \leq 153^\circ\text{C}$	
$I_{FSM}$	Non-Repetitive Forward Surge Current	50	A	$T_J = 25^\circ\text{C}$ , $t_p = 8.3\text{ms}$ , Half Sine Wave	
$P_{tot}$	Power Dissipation	107	W	$T_J = 25^\circ\text{C}$	Fig. 3
$T_J, T_{STG}$	Operating Junction and Storage Temperature	-55 to 175	$^\circ\text{C}$		

## Electrical Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$V_F$	Forward Voltage	1.4 1.7	1.65 2.3	V	$I_F = 8A, T_J = 25^\circ C$ $I_F = 8A, T_J = 175^\circ C$	Fig. 1
$I_R$	Reverse Current	1 5	20 100	$\mu A$	$V_R = 650V, T_J = 25^\circ C$ $V_R = 650V, T_J = 175^\circ C$	Fig. 2
C	Total Capacitance	520 50 41	/	pF	$V_R = 0V, T_J = 25^\circ C, f = 1MHz$ $V_R = 200V, T_J = 25^\circ C, f = 1MHz$ $V_R = 400V, T_J = 25^\circ C, f = 1MHz$	Fig. 5
$Q_C$	Total Capacitive Charge	22	/	nC	$V_R = 650V, I_F = 8A$ $di/dt = 200A/\mu s, T_J = 25^\circ C$	Fig. 4

## Thermal Characteristics

Symbol	Parameter	Typ.	Unit	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	1.4	$^\circ C/W$	Fig. 6
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	80	$^\circ C/W$	
$T_{sold}$	Soldering Temperature	260	$^\circ C$	

## Typical Performance

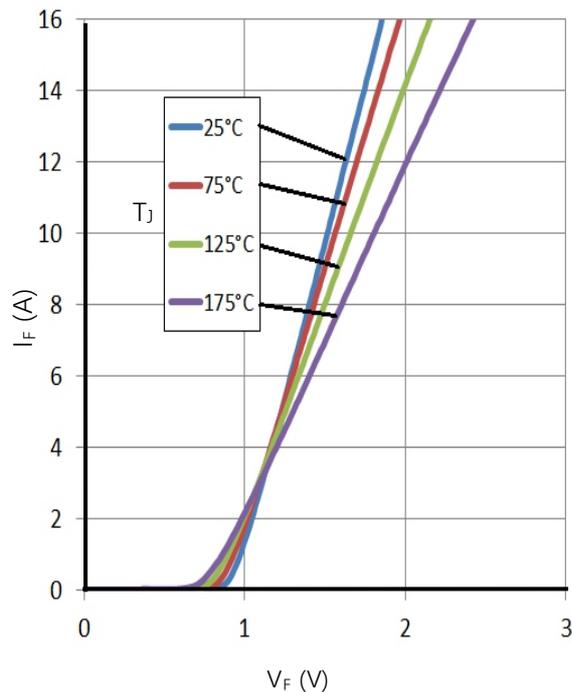


Figure 1. Forward Characteristics

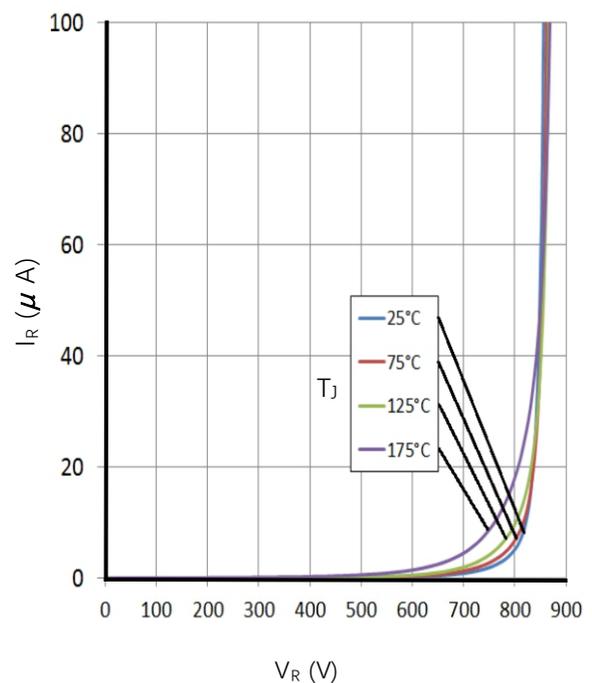


Figure 2. Reverse Characteristics

## Typical Performance

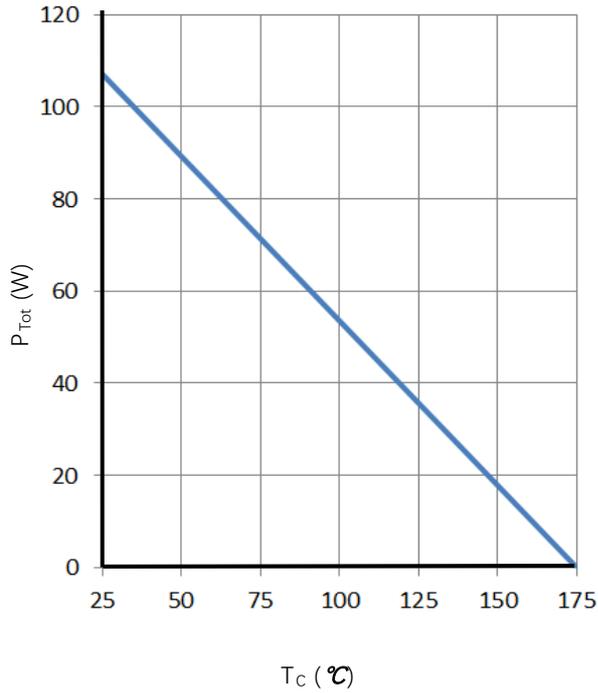


Figure 3. Power Derating

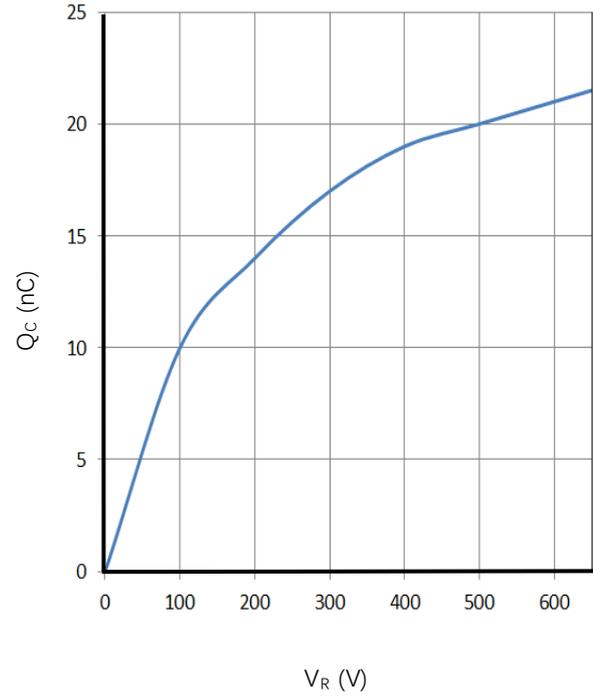


Figure 4. Total Capacitive Charge vs. Reverse Voltage

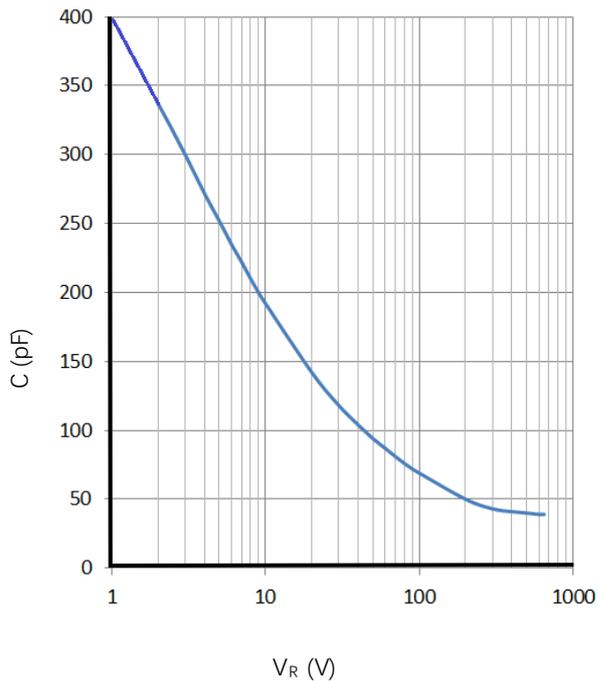


Figure 5. Total Capacitance vs. Reverse Voltage

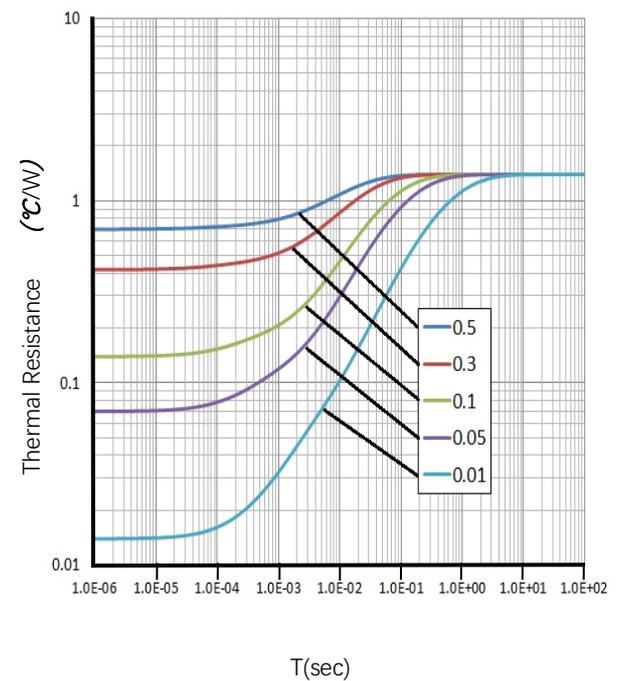


Figure 6. Transient Thermal Impedance

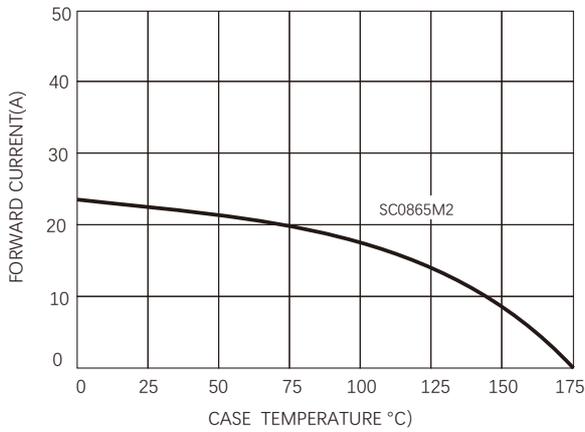
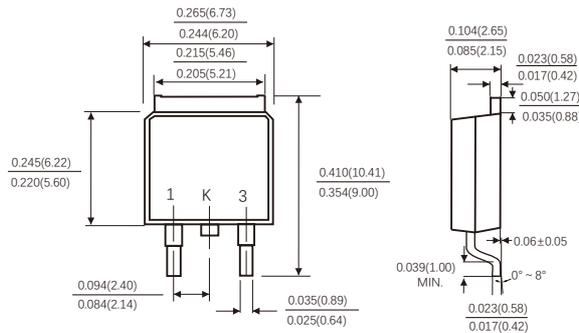


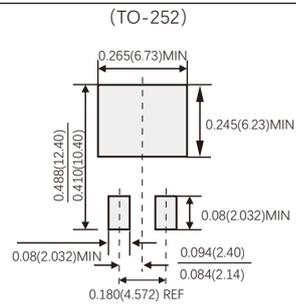
FIG.7-FORWARD CURRENT DERATING CURVE

## PACKAGE DIMENSIONS

### TO-252



### Suggested Pad Layout



(设计者可参考推荐值根据焊接工艺要求自行确定适合的焊盘尺寸)  
 (Designers can refer to the recommended values according to the manufacturing process requirements to determine the appropriate pad size)

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